

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10620002
<b>Filing Date:</b>	14-Jul-2003
<b>Title of Invention:</b>	SLURRY FOR USE WITH FIXED-ABRASIVE POLISHING PADS IN POLISHING SEMICONDUCTOR DEVICE CONDUCTIVE STRUCTURES THAT INCLUDE COPPER AND A COPPER BARRIER
<b>First Named Inventor/Applicant Name:</b>	Dinesh Chopra
<b>Filer:</b>	Brick Glenn Power/Sharley Thayne
<b>Attorney Docket Number:</b>	2269-4373.2US (00-0036.02)

Filed as Large Entity

### **Utility Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

Post-Allowance-and-Post-Issuance:

**Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>810</b>